

## General purpose PIN diode

### FEATURES

- Two elements in series configuration in a small SMD plastic package
- Low diode capacitance
- Low diode forward resistance.

### APPLICATIONS

- General RF applications.

### DESCRIPTION

Two planar PIN diodes in series configuration in an SOT323 small SMD plastic package.

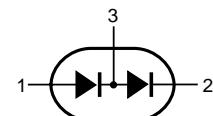
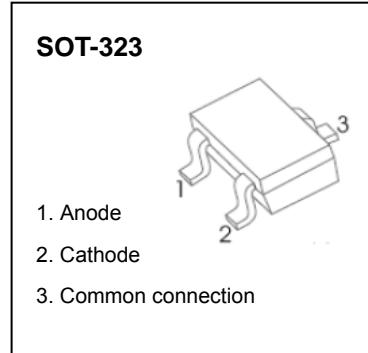


Fig.1 Simplified outline (SOT323) and symbol.

**Marking code:** 6W

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
<b>Per diode</b>					
V <sub>R</sub>	continuous reverse voltage		–	50	V
I <sub>F</sub>	continuous forward current		–	50	mA
P <sub>tot</sub>	total power dissipation	T <sub>s</sub> = 90 °C	–	240	mW
T <sub>stg</sub>	storage temperature		–65	+150	°C
T <sub>j</sub>	junction temperature		–65	+150	°C

**ELECTRICAL CHARACTERISTICS**
 $T_j = 25^\circ C$  unless otherwise specified.

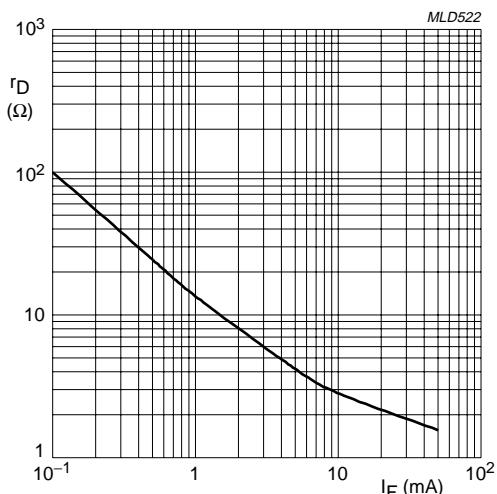
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Per diode</b>						
$V_F$	forward voltage	$I_F = 50 \text{ mA}$	–	0.95	1.1	V
$V_R$	reverse voltage	$I_R = 10 \mu\text{A}$	50	–	–	V
$I_R$	reverse current	$V_R = 50 \text{ V}$	–	–	100	nA
$C_d$	diode capacitance	$V_R = 0; f = 1 \text{ MHz}$	–	0.45	–	pF
		$V_R = 1 \text{ V}; f = 1 \text{ MHz}$	–	0.35	0.6	pF
		$V_R = 5 \text{ V}; f = 1 \text{ MHz}$	–	0.30	0.5	pF
$r_D$	diode forward resistance	$I_F = 0.5 \text{ mA}; f = 100 \text{ MHz}; \text{note 1}$	–	25	40	$\Omega$
		$I_F = 1 \text{ mA}; f = 100 \text{ MHz}; \text{note 1}$	–	14	25	$\Omega$
		$I_F = 10 \text{ mA}; f = 100 \text{ MHz}; \text{note 1}$	–	3	5	$\Omega$
$\tau_L$	charge carrier life time	when switched from $I_F = 10 \text{ mA}$ to $I_R = 6 \text{ mA}$ ; $R_L = 100 \Omega$ ; measured at $I_R = 3 \text{ mA}$	–	1.05	–	$\mu\text{s}$
$L_S$	series inductance	$I_F = 10 \text{ mA}; f = 100 \text{ MHz}$	–	1.60	–	nH

**Note**

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

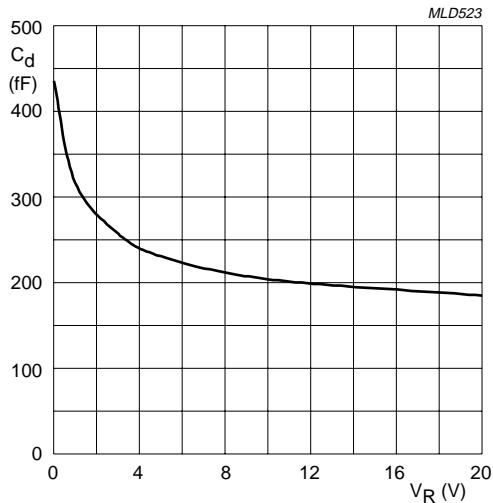
**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th j-s}$	thermal resistance from junction to soldering point	250	K/W

**GRAPHICAL DATA**


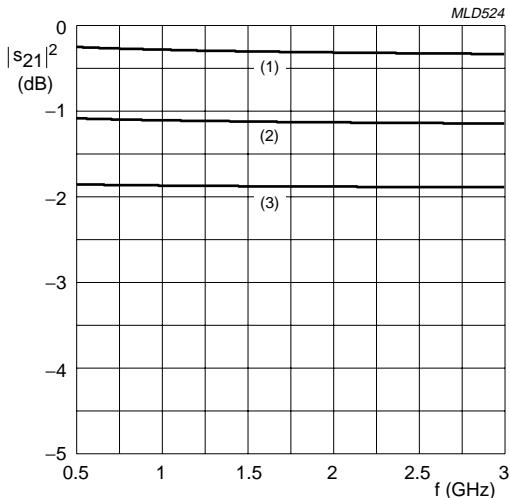
$f = 100 \text{ MHz}; T_j = 25^\circ\text{C}$ .

Fig.2 Forward resistance as a function of forward current; typical values.



$f = 1 \text{ MHz}; T_j = 25^\circ\text{C}$ .

Fig.3 Diode capacitance as a function of reverse voltage; typical values.

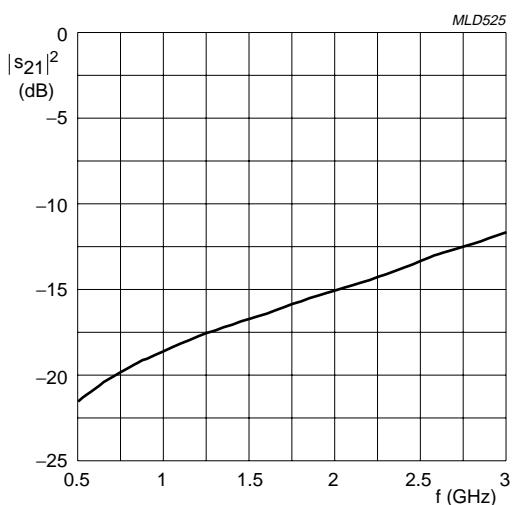


(1)  $I_F = 10 \text{ mA}$ . (2)  $I_F = 1 \text{ mA}$ . (3)  $I_F = 0.5 \text{ mA}$ .

Diode inserted in series with a  $50 \Omega$  stripline circuit  
and biased via the analyzer Tee network.

$T_{\text{amb}} = 25^\circ\text{C}$ .

Fig.4 Insertion loss ( $|s_{21}|^2$ ) of the diode in on-state  
as a function of frequency; typical values.



Diode zero biased and inserted in series with a  $50 \Omega$  stripline circuit.  
 $T_{\text{amb}} = 25^\circ\text{C}$ .

Fig.5 Isolation ( $|s_{21}|^2$ ) of the diode in off-state as a  
function of frequency; typical values.